

Title (en)

Equipment and method for cleaning polishing cloth

Title (de)

Ausrüstung und Verfahren zum Reinigen eines Polierlappens

Title (fr)

Équipement et procédé pour le nettoyage d'un tissu de polissage

Publication

**EP 2236245 A3 20130911 (EN)**

Application

**EP 10250452 A 20100311**

Priority

JP 2009079630 A 20090327

Abstract (en)

[origin: EP2236245A2] The equipment (34) for cleaning polishing cloth (16) is capable of increasing pressure of washing water received by the polishing cloth (16), securely removing deposits from the polishing cloth (16) and improving polishing efficiency. The equipment (34) is used in a polishing apparatus (10), in which a work piece (20) is pressed onto the polishing cloth (16) adhered on a polishing plate (12) and the work piece (20) is relatively moved with respect to the polishing plate (12) with supplying slurry to the polishing cloth (16) so as to polish the work piece (20). The equipment (34) comprises a nozzle unit (48) having a nozzle (50) capable of spraying high-pressure washing water toward the polishing cloth (16). The nozzle (50) is a straight nozzle capable of linearly spraying the washing water and perpendicularly spraying the washing water with respect to the polishing cloth (16).

IPC 8 full level

**B24B 37/04** (2012.01); **B24B 53/007** (2006.01); **H01L 21/304** (2006.01)

CPC (source: EP US)

**B24B 53/017** (2013.01 - EP US)

Citation (search report)

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**EP 10250452 A 20100311**; CN 201010141121 A 20100325; JP 2009079630 A 20090327; KR 20100026642 A 20100325; TW 99107177 A 20100312; US 73290410 A 20100326